

## ABSTRACT OF THE DISCLOSURE

A substrate assembly including a substrate and a plurality of spring-biased electrical contacts formed thereon for establishing electrical contact with the lead elements of an IC device. The substrate assembly also comprises a layer of resilient conductive material formed on a surface of the substrate, the spring-biased electrical contacts being formed in the resilient conductive material layer in situ on the substrate. Each spring-biased electrical contact includes a surface or surfaces configured to bias against and electrically contact an IC device lead element. The present invention also encompasses methods of fabricating substrate assemblies according to the invention, including heat treating the substrate assembly after formation to achieve desired spring characteristics.

N: 2269 4322 patent application.wpd 8/29/01